

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	§	
Chad A. Cobbley et al.	§	Confirmation No. 1056
	§	
Serial No.: 10/672,750	§	Group Art Unit: 2813
	§	
Filed: September 25, 2003	§	Examiner: Mitchell, James M.
	§	
For: STACKED DIE MODULE AND	§	Atty Docket:
TECHNIQUES FOR FORMING A	§	MICS:0078-1/FLE/MAN
STACKED DIE MODULE USING	§	(01-0752.01)
MULTIPLE ADHESIVES THAT CURE	§	
AT DIFFERENT TEMPERATURES	§	
(amended)	§	

Mail Stop Amendment
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

<p align="center">CERTIFICATE OF MAILING 37 C.F.R. 1.8</p>	
<p>I hereby certify that this correspondence is being transmitted by facsimile to the United States Patent and Trademark Office in accordance with 37 C.F.R. § 1.6(d), or is being transmitted via the Office electronic filing system in accordance with 37 C.F.R. § 1.6(a)(4), or is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:</p>	
<p>December 4, 2008</p>	<p>/W. Allen Powell/</p>
<p>Date</p>	<p>W. Allen Powell</p>

RESPONSE TO OFFICE ACTION MAILED SEPTEMBER 5, 2008

In response to the Office Action mailed September 5, 2008, Applicants respectfully request reconsideration of the above-identified application in view of the amendments and remarks set forth below.